Precision Clamps and Heat Sink Assemblies

Heat Sink SCR IGBT Assemblies

Wakefield-Vette compression pack heat sink and clamp systems provide customers with the complete system solution for proper installation and heat dissipation for high-power compression pack semiconductors. These high-quality mounting clamp assemblies are the industry standard for mounting, compressing, and clamping press-pack SCR, thyristors, rectifiers, and other high power disc packaged devices. Devices of these styles are most commonly found in power distribution equipment, industrial controls, transportation systems, and power supply and conversion systems.

A clamp system consists of a crossbar and a spring assembly. The crossbar is a steel bar with two threaded rods installed in it. The rods are generally knurled and cold rolled into the bar to ensure proper fit. The cross bar assembly is covered in an epoxy coating which acts as an electrical insulator to ensure the devices are properly grounded. The crossbar is installed through the center web of the heat sink and sits in a channel surrounded by fins needed for thermal performance.

On the back of the heat sink, a puck style device is installed and then the spring assembly is installed in the threaded rods of the crossbar. By tightening the nuts on the spring assembly, a compression force is applied to the center of the puck. Each spring assembly has a force gauge integrated into it to ensure ease of assembly and consistency of force applied to the many devices used in a system.

The cross bar assembly is available in various lengths to meet the various needs of the industry. All components for device mounting are available separately for all standard compression requirements from 800 lbs. to 16,000 lbs.













PRECISION COMPRESSION MOUNTING CLAMP SYSTEMS

Wakefield-Vette Engineering compression pack heat sinks and clamp systems provide electrical and industrial equipment manufacturers with complete system solutions for proper installation and heat dissipation for high-power compression pack semiconductor. All components for device mounting and cooling are available separately for all standard compression requirements from 800 lbs (362.9 kg) to 16,000 lbs (7,257.5 kg) force in both natural and forced convection applications.

Clamp Assembly	Maximum Clamping Force	Maximum Diameter (Ref)	Crossbar Stud Centerline to Centerline Dimension
Series	Force Range	Power Disc Device	
130 Series 139 Series 143 Series 144 Series 145 Series 146 Series 131/132/133 Series	800 lbs (362.9 kg) - 2,000 lbs (907.2 kg) 3,000 lbs (1,360.8 kg) and 5,000 lbs (2,268.0 kg) 1,000 lbs (453.6 kg) - 6,000 lbs (2,721.6 kg) 1,000 lbs (453.6 kg) - 6,000 lbs (2,721.6 kg) 2,000 lbs (907.2 kg) - 10,000 lbs (4,535.9 kg) 8,000 lbs (3,628.8 kg) - 16,000 lbs (7,257.5 kg) High-Performance Press Pack Heat Sinks	2.25 in. (57.2 mm) 3.50 in. (88.9 mm) 3.50 in. (88.9 mm) 4.00 in. (101.6 mm) 4.50 in. (114.3 mm) 5.25 in. (133.4 mm)	2.750 in. (69.9 mm) Ref 4.000 in. (101.6 mm) Ref 4.000 in. (101.6 mm) Ref 4.625 in. (117.5 mm) Ref 5.500 in. (139.7 mm) Ref 6.000 in. (152.4 mm) Ref

These high-quality mounting clamp assemblies are the worldwide standard for mounting, compression, and clamping press-pack SCR, thyristor, rectifier, and other high power disc packaged devices utilized in power distribution equipment, industrial controls, transportation systems, and power supply and conversion systems.

Clamp assemblies will accommodate devices with overall case diameters to 5.25 in. (133.4 mm) maximum. Vertical device mounting space available for assemblies is determined by selecting an appropriate series crossbar by length which, when a series spring assembly is selected (based on maximum clamping force required), will provide the necessary vertical clearance space. For the 130 and 139 Series, this determination is made by subtracting the chosen spring assembly "Z" dimension (refer to dimensional tables) from the crossbar assembly "X" dimension minimum and maximum values, to calculate the available device mounting space clearance for the particular assembly combination. Spring assembly "Z" dimension is the dimension measured from the spring assembly device mounting surface to the spring assembly top surface. Some series have fixed dimensions for alpha characters. All spring assemblies are designed with a force indicator gauge.

Max SCR DIA	Clamp Series	Force Range	Extrusion Profile
101.6 mm	ALL	800 - 16000 LBS	XX7151
84 mm	ALL	800 - 16000 LBS	XX6351
63 mm	ALL 144 143 144 144 143 143 143 143	800 - 16000 LBS 800 - 6000 LBS	XX5735 XX5360 XX10239 O16235 O14442 XX3529 XX5730 O14191 XX3849
50 mm	143 143 143 143 143 143 143 143 143 143	800 - 6000 LBS 800 - 6000 LBS	XX5733 XX3559-2 XX5736 XX3561-2 XX5731 XX5731 XX3560-2 O13450 XX4554 XX5331 OO3537 XX5306
40 mm	143	800 - 6000 LBS	014779



130 SERIESCOMPRESSION MOUNTING CLAMP ASSEMBLIES FOR
SEMICONDUCTORS TO 2.25 IN. (57.2 MM) DIAMETER

800 lb - 2,000 lb (362.8 kg - 907.2 kg)					
Crossbar D Top Surface	evice Mounting, Sur e Dimension	face to Spring Asser	mbly		
Model No.	"X" Dimension Model Min. Max. No. in. (mm) in. (mm)				
130-A	1.74 (44.2)	2.12 (53.8)	0.4 (181.44)		
130-B	2.05 (52.1)	2.43 (61.7)	0.418 (189.60)		
130-C	2.36 (59.9)	2.74 (69.6)	0.427 (193.68)		
130-D	2.67 (67.8)	3.05 (77.5)	0.437 (198.22)		
130-E	2.98 (75.7)	3.36 (85.3)	0.447 (202.76)		
130-F	3.29 (83.6)	3.67 (93.2)	0.461 (209.11)		
130-G	3.60 (91.4)	3.98 (101.1)	0.476 (215.91)		
130-H	3.91 (99.3)	4.29 (109.0)	0.486 (220.45)		
130-J	4.22 (107.2)	4.60 (116.8)	0.497 (225.44)		
130-K	4.53 (115.1)	4.91 (124.7)	0.51 (231.33)		
130-L	4.34 (122.9)	5.22 (132.6)	0.52 (235.87)		
130-M	5.15 (130.8)	5.53 (140.5)	0.534 (242.22)		
130-N	5.46 (138.7)	5.84 (147.3)	0.544 (246.75)		
130-P	5.77 (146.6)	6.15 (156.2)	0.559 (253.56)		

MECHANICAL DIMENSIONS



Dimensions: in. (mm)



PRECISION COMPRESSION MOUNTING CLAMP SYSTEMS

143 SERIES

COMPRESSION MOUNTING CLAMP ASSEMBLIES FOR SEMICONDUCTORS TO 3.50 IN. (88.9 MM) DIAMETER



143 SERIES CROSSBAR 2,000 lb - 6,000 lb (907.2 kg - 2,721.6 kg) Crossbar Device Mounting, Surface to Spring Assembly, Top Surface Dimension "X" Dimension Overall Model Min Max Height "H" in. (mm) No. in. (mm) in. (mm) 1.30 (33.0) 143-A 1.80 (45.7) 4.68 (118.9) 143-B 1.86 (45.7) 2.30 (58.4) 5.18 (131.6) 143-C 2.30 (58.4) 2.80 (71.1) 5.68 (144.3)

143-B	1.86 (45.7)	2.30 (58.4)	5.18 (131.6)	1.125 (510.29)
143-C	2.30 (58.4)	2.80 (71.1)	5.68 (144.3)	1.150 (521.63)
143-D	2.80 (71.1)	3.30 (83.8)	6.18 (157.0)	1.175 (532.97)
143-E	3.30 (83.8)	3.80 (96.5)	6.68 (169.7)	1.200 (544.31)
143-F	3.80 (96.5)	4.30 (109.2)	7.18 (182.4)	1.225 (555.65)
143-G	4.30 (109.2)	4.80 (121.9)	1.68 (195.1)	1.250 (566.99)
143-H	4.80 (121.9)	5.30 (134.6)	8.18 (207.8)	1.275 (578.33)
143-J	5.30 (134.6)	5.80 (147.3)	8.68 (220.5)	1.300 (589.67)
143-K	5.80 (147.3)	6.30 (160.0)	9.18 (233.2)	1.325 (601.00)
143-L	6.30 (160.0)	6.80 (172.7)	9.68 (245.9)	1.350 (612.35)

143 SERIES SPRING ASSEMBLY Model Number of Max. Clamping Weight Number Leaves Force lb. (kg) lb. (grams) 143-2 0.813 (368.77) 2 6,000 (2,721.6)

Order Guide:

Dimensions:

Weight

lbs. (grams)

1.100 (498.95)

Order Crossbar and Spring Assembly separately by type number from table.

in. (mm)

lb. (kg)

MECHANICAL DIMENSIONS



Dimensions: in. (mm)



PRECISION COMPRESSION MOUNTING CLAMP SYSTEMS



146 SERIES

COMPRESSION MOUNTING CLAMP ASSEMBLIES FOR SEMICONDUCTORS TO 5.25 IN. (133.5 MM) DIAMETER

MECHANICAL DIMENSIONS

146 SERIES CROSSBAR 8,000 lb-16,000 lb (3,628.7 kg - 7,257.4 kg)					
Crossbar I	Device Mounting, S	Surface to Spring A	ssembly, Top Surfac	e Dimension	
	"X" Din	nension	Overall		
Model No.	Min in. (mm)	Max in. (mm)	Height "H" in. (mm)	Weight lbs. (grams)	
146-A 146-B 146-C 146-D 146-E 146-F 146-G	1.54 (39.1) 2.29 (58.2) 3.04 (77.2) 3.79 (96.3) 4.54 (115.3) 5.29 (134.4) 6.04 (153.4)	2.29 (58.2) 3.04 (77.2) 3.79 (96.3) 4.54 (115.3) 5.29 (134.4) 6.04 (153.4) 6.79 (172.5)	5.92 (150.4) 6.67 (169.4) 7.42 (188.5) 8.17 (207,5) 8.92 (226.6) 9.67 (245.6) 10.42 (264.7)	3.813 (1729.55) 3.938 (1786.25) 4.063 (1842.95) 4.188 (1899.64) 4.313 (1956.34) 4.438 (2013.04) 4.563 (2069.74)	

146 SERIES SPRING ASSEMBLY

Model Number of		Clamping Force Range	Maximum Force	
Number Leaves		lb. (kg)	lb. (grams)	
146-2	2	8,000 (3,628.7) - 16,000 (7,257.5)	2,688 (1,219.26)	

Order Guide:

Order Crossbar and Spring Assembly separately by type number from table.

Dimensions:

lb. (kg)



Dimensions: in. (mm)

132/133 SERIES HIGH-PERFORMANCE HEAT SINKS FOR COMPRESSION TYPE DEVICES

						Thermal Pe at Typica	erformance al Load ⁽²⁾
Standa Black Anodize ^(4, 5)	rd P/N Gold Iridite	Width in. (mm)	Nominal Dimensions: ⁽¹⁾ Length "A" in. (mm)	Height in. (mm)	Clamp System Series ⁽⁵⁾	Natural Convection (°C/W) ⁽³⁾	Convection (°C/W)@ 500 LFM)
132-4.5B 132-10B 132-15.5B 132-5-B9 132-11-B9 133-4.5B 133-7.5B 133-7.5B 133-10B 133-5-B9 133-7.5-B9 133-7.5-B9	132-4.5G 132-10G 132-5.69 132-5.69 132-11-69 133-4.5G 133-7.5G 133-10G 133-5.69 133-7.5-69 133-11-69	5.000 (127.0) 5.000 (127.0) 5.000 (127.0) 5.000 (127.0) 7.000 (139.2) 7.000 (139.2) 7.000 (139.2) 7.000 (139.2) 7.000 (139.2) 7.000 (139.2)	4.500 (114.3) 10.000 (254.0) 15.500 (393.7) 5.000 (127.0) 11.000 (299.4) 4.500 (114.3) 7.500 (190.5) 10.000 (254.0) 5.000 (127.0) 7.500 (190.5) 11.000 (279.4)	2.250 (57.2) 2.250 (57.2) 2.250 (57.2) 2.250 (57.2) 3.125 (79.4) 3.125 (79.4) 3.125 (79.4) 3.125 (79.4) 3.125 (79.4) 3.125 (79.4) 3.125 (79.4)	130 130 139 139 130 130 130 130 139 139 139	0.61 0.38 0.28 0.61 0.37 0.28 0.26 0.37 0.28 0.24	0.170 0.130 0.100 0.170 0.120 0.110 0.085 0.082 0.110 0.085 0.085 0.076
Material: Aluminum, Black Anodized Finish: B = Black Anodized, G = Gold Iridite							

132 & 133 SERIES



wakefield-vette

Clamp Assembly Procedure

All illustrations assume the following parts: 143 series crossbar, 143-2 spring leaf assembly and one or two 132-5-B9 heat sinks, compression SCR (not a Wakefield product), EJC No. 2 thermal joint compound (not a Wakefield product). Wakefield recommends using two heat sinks, one on each side of the SCR.

When received, the top edges of the force indicator should be in line with bottom edge of the spring leaf as shown below. This is the zero position. If this is not the case, move it to zero with your hands or a pair of pliers.



If using one heat sink only: The roll pin will need to be adjusted to fit into the blind hole of the SCR. Check the depth of the blind hole and allow a clearance of at least 0.025 in (0.65 mm). Care will be needed to ensure that the upper retaining washer is held against the top leaf spring.



www.wakefield-vette.com



Clamp Assembly Procedure

If using two heat sinks on both sides of the component: place the heat sink on a flat surface and put the leaf spring assembly between the fins on center with the roll pin into the hole. With a hammer drive the pin into the hole and through the heat sink, so that the pin comes through the other side and protrudes 0.050 in (1.3 mm). This is helpful in indexing the SCR to keep it concentric to the forces applied when the nuts are tightened. This also holds the spring leaf assembly in place.



Apply a <u>non-silicone</u> based thermal compound to the spotface of the heat sink <u>without</u> the spring leaf assembly/roll pin. It is recommended that Electrical Joint Compound No. 2 (EJC #2) be used, as it contains a fluoride compound that removes the surface oxides on both the heat sink surface and the pole face of the SCR. Do not use Wakefield Type 120 compound, as it will cause a hot spot at this joint. There are many methods for applying the proper thickness of grease with full coverage and without excessive squeeze-out; this should be done by trial and error, removing the SCR and checking the amount of coverage.

Electrical Joint Compound No. 2 (EJC #2) is supplied by:

ACA Conductor Accessories <u>www.acasolutions.com</u> (800) 866-7385



Apply thermal joint compound to hatched area

www.wakefield-vette.com



Clamp Assembly Procedure

Apply the thermal compound to the spotface of the heat sink <u>with</u> the spring leaf assembly and place the SCR in position on the spotface, centering the SCR on the roll pin. At this time fit the crossbar studs between the two innermost fins and through the holes of the other heat sink (without the spring leaf assembly). Slowly drop the crossbar studs through the holes in the heat sink with the SCR and spring leaf assembly, making sure that the SCR fits over the spotface on the upper heat sink. Then flip the assembly upside down, supporting the crossbar against the inner surface of the heat sink. Drop the washers over the threaded ends of the studs, and then apply the nuts to the threads and screw on until finger tight.





Clamp Assembly Procedure

Tighten the nuts alternately one-quarter turn each until you have reached the required force recommended for the SCR. This occurs when the edge of the marked step on the force indicator matches the bottom edge of the spring leaf as shown below.



Additional notes:

Avoid short cuts in assembling these components, as it is important that deflection of the spring leaf assembly be given precedence over all other choices of force measuring techniques.

Do not use torque wrenches to set the force level, as torque is not a measure of force on these assemblies. The lubricants and surfaces of the nuts and washers will vary and cause a gross misrepresentation of force if torque is used as a force indicator.

Spotfaces are machined to a minimum depth to provide a flat surface for the SCR to sit on. The pole face of the SCR is only about 0.060 in (1.5 mm) above the surrounding bellows ring that is bonded to the SCR porcelain housing. The pole faces of the SCR deflect slightly as the force is applied to make contact to the silicon dioxide disc inside. If the spotface is too deep on the heat sink, the shoulder of the bellows will make contact to the heat sink, and the proper force required at the pole faces will not be met.

Every clamp/heat sink/SCR assembly will not have the same physical heat sink thicknesses to accommodate, and will require that the customer install small pins into the heat sinks to index the SCRs. The pins in the leaf spring assemblies will not be long enough in most cases and cannot be driven through the thicker heat sinks. In these applications the pin is driven into the heat sink a minimum distance to lock the leaf spring assembly to the heat sink.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Heat Sinks category:

Click to view products by Wakefield manufacturer:

Other Similar products are found below :

 581102B00000G
 656-15ABPE
 657-20ABPNE
 7020B-TC12-MTG
 73452PPBA
 7G0011A
 PF720G
 A22-4026
 120-1873-007
 HAH10L

 HAH15L
 1542616-1
 HS-2506-F1
 HS-87M0-F2
 218-40CTE3
 231-69PAB-15V
 25-7520
 SW50-4G
 231-75PAB-13V
 231-75PAB-15V
 253

 122ABE-22
 PSC22CB
 HAF10L
 HAQ10T
 D10100-28
 BDN183CBA01
 3-21053-4
 32438
 TX0506-1B
 TX1806B
 LAE66A3CB
 WA-DT2

 101E
 511-3U
 73381PPBA
 73403PPBA
 7G0047C
 COMX-440-HSP
 510-12M
 D10650-40T5
 V8511 Y
 APF40-40-13CB/A01

 780653U04500G
 ATS-54310K-C2-R0
 FK 216 CB SA
 FK 231 SA 220
 648-51AB
 657-20ABPESC
 2341BG
 679-25AG
 FK 212 CB SA